

# POWERVIA™ SURVEY

PowerVia posts allow the soldering of power devices directly to aluminum “thermal transfer columns”. The PowerVias are pre-installed in the PCB, so the entire PCB assembly is then merely bolted to the heat sink (no interface pressure dependency). PowerVias offer excellent thermal performance and electrical isolation.

APPLICATION PROFILE		
Application description	_____	Power supply (AC/DC, DC/DC, inverter, UPS), Motion control, Motor control, etc.
Unit size	_____	Watts (power supply), Amps (motion control)
Design location(s) (specification)	_____	Ex., California, Germany, etc.
Manufacturing location(s)	_____	Ex., New Jersey, Taiwan, etc.
SUBASSEMBLY PROFILE		
Number of devices used annually (est.)	_____ _____ _____	D2Pak TO-220 TO-247 or D3Pak Other
Waste heat per device (typical / peak)	_____/_____ _____/_____	D2Pak or TO-220 TO-247 or D3Pak
<p><b>NOTE:</b> EZ waste heat estimation formula:  <math>WASTE\ HEAT\ per\ device = Power \times (100\% - Unit\ efficiency) / Number\ of\ power\ devices</math>            [NOTE: Device types = FET, diode, IGBT, etc.]</p>		
How many power devices per PCB?	_____	
Are devices mounted on one or both sides of the PCB?	_____	
Present attachment method (board-to-sink)	_____	Screw, clip, bar, etc.
Present interface material  (Choose one or more)	_____ _____ _____ _____	Pad type (please specify) Other type (please specify) Devices not electrically-isolated Case-isolated devices used (ex., Iso-Pak)

Biggest concerns about subassembly  (in order of priority, 1=biggest)	_____ _____ _____ _____	Device temperature Electrical isolation integrity Labor cost and consistency Design flexibility
Power device failures now mainly due to.....	_____	
How would you use the improvement in thermal performance and or design flexibility?  (in order of priority 1-6. 1=highest)	_____ _____ _____ _____ _____	Cooler power device (same part number) Run unit at higher power, with same devices Cheaper power device (different part number) Less devices in assembly (assuming parallel operation) Higher ambient rating of unit Smaller heat sink
NEW TECHNOLOGY ADOPTION		
Would you consider PowerVia technology for...?	_____ _____ _____	Existing design New design under development Future design
How long does your company require to....?	_____ _____ _____	Qualify new technology (months) Design=>commercialization Introduce new unit (conceptualization=>market)
POWERVIA SUPPLY CHAIN		
OEM supply chain:	_____ _____ _____	In-house total assembly Contract PCB assembly only Contract total assembly

Mail the completed survey to EIS Fabrico and receive:

- PowerVia prototype samples
- PowerVia technical bulletin
- PowerVia product brochure
- Entry in drawing for prestigious “PowerVia polo shirt”

No purchase necessary.